



INITIAL PRODUCT/PROCESS CHANGE NOTIFICATION #20730Generic Copy

Issue Date: 13-Jan-2015

TITLE: Back Grind/Back Metal Capacity Expansion at the ON Semiconductor Wafer Fab (CZ4) located in Roznov, Czech Republic.

PROPOSED FIRST SHIP DATE: 20-May-2015

AFFECTED CHANGE CATEGORY(S): ON Semi Wafer Fab Site and assembly sites

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact your local ON Semiconductor Sales Office or following Contact Sales and Marketing and Product Engineers:

IPCN Contact Person by Affected Technology:

IGBT3	Sales / Marketing	Richard White	Richard.White@onsemi.com
	Product Engineering	Marc Fillion	Marc.Fillion@onsemi.com
IGBT4	Sales / Marketing	Richard White	Richard.White@onsemi.com
	Product Engineering	Marc Fillion	Marc.Fillion@onsemi.com

NOTIFICATION TYPE:

Initial Product/Process Change Notification (IPCN)

First change notification sent to customers. IPCNs are issued at least 120 days prior to implementation of the change. An IPCN is advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.

The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN).

This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change.



INITIAL PRODUCT/PROCESS CHANGE NOTIFICATION #20730

DESCRIPTION AND PURPOSE:

ON Semiconductor is pleased to announce the intent to implement in the third quarter of the year 2015 a back grind & back metal capacity expansion at the CZ4 Wafer Fab at Roznov, Czech Republic. This expansion will supplement the current back grind & back capability ISMF Fab in Seremban, Malaysia.

Upon expiration of the associated Final PCN(s), the back grind & back metal for the affected devices could be processed from either the ISMF or CZ4 wafer fab.

QUALIFICATION PLAN:

Full qualification testing will be performed on representative devices or family of devices as necessary to ensure compliance to all existing ON Semiconductor reliability requirements. Specific plans and qualification results for each device family will be announced via individual Final PCN's as those qualifications are achieved.

Qualification Vehicles:

- NGD8201A
- NGD18N40A

Reliability testing for each qualification vehicle may include the following:

Reliability Test:

Test	Test Conditions	Read points	Sample Size
PC-SAT	Scanning Acoustic Tomography	T0 and Post TC	3 lots x 10 units
PC-TC	-55 C to 150 C for 1000 cycles	Test @ 0, 500, 1000	3 lots x 80 units
DPA		Post TC1000	2 Units from 1 Lot
PC-HAST	130°C/85% RH, 18.8 PSI for 96 hrs biased	T96, Test at R	3 lots x 80 units
DPA		Post HAST	2 Units from 1 Lot
RSH	Loose Units		30 units
HTRB	TJ = 150°C for 1000 hrs, 80% Bias	Test @ 500, 1000	3 lots x 80 units
IOL	3.5 min On/Off, $\Delta T > 100$ C	Test @ IOL4286, IOL8572	3 lots x 80 units
PV	Parametric Verification, Test @ R,H,C	>1.67 Cpk	3 lots x 30 units
ESD	ESD HBM	1/V per Model	10 units
UIS	Unclamped Inductive Switching	Test at room	5 Units



INITIAL PRODUCT/PROCESS CHANGE NOTIFICATION #20730

List of affected General Parts:

NGB15N41ACLT4G
NGB18N40ACLBT4G
NGB8202ANT4G
NGB8204ANT4G
NGB8206ANSL3G
NGB8206ANT4G
NGB8206ANTF4G
NGB8207ABNT4G
NGB8207BNT4G
NGB8245NT4G
NGD15N41ACLT4G
NGD18N40ACLBT4G
NGD18N45CLBT4G
NGD8201ANT4G
NGD8201BNT4G
NGD8205ANT4G
NGD8209NT4G

List of affected Customer Specific Parts:

SGB8206ANSL3G
SGB8206ANT4G
SGB8206ANTF4G
SGD8290NT4G